

1 **DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

2 As the below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated
4 below next to my name.

5 I believe I am the original, first and joint inventor of the subject
6 matter which is claimed and for which a patent is sought on the
7 invention entitled: Methods Of Forming Materials Between Conductive
8 Electrical Components, And Insulating Materials, the specification of
9 which is attached hereto.

10 I hereby state that I have reviewed and understand the contents
11 of the above-identified specification, including the claims.

12 I acknowledge the duty to disclose information known to me to
13 be material to patentability as defined in Title 37, Code of Federal
14 Regulations §1.56.

15 **PRIOR FOREIGN APPLICATIONS:**

16 I hereby state that no applications for foreign patents or inventor's
17 certificates have been filed prior to the date of execution of this
18 declaration.

19 **POWER OF ATTORNEY:**

20 As a named Inventor, I hereby appoint the following attorneys and
21 agent to prosecute this application and transact all business in the
22 Patent and Trademark Office connected therewith: Richard J. St. John,
23 Reg. No. 19,363; David P. Roberts, Reg. No. 23,032; Randy A. Gregory,
24 Reg. No. 30,386; Mark S. Matkin, Reg. No. 32,268; James L. Price, Reg.

1 No. 27,376; Deepak Malhotra, Reg. No. 33,560; Mark W. Hendrickson,
2 Reg. No. 32,356; David G. Latwesen, Reg. No. 38,533; George G.
3 Grigel, Reg. No. 31,166; Keith D. Grzelak, Reg. No. 37,144; John S.
4 Reid, Reg. No. 36,369; Lance R. Sadler, Reg. No. 38,605; James D.
5 Shaurette, Reg. No. 39,833; Lia Pappas Dennison, Reg. No. 34,095; and
6 Michael L. Lynch, Reg. No. 30,871.

7 Send correspondence to: WELLS, ST. JOHN, ROBERTS,
8 GREGORY & MATKIN P.S., 601 W. First Avenue, Suite 1300, Spokane,
9 WA 99204-0317. Direct telephone calls to: David G. Latwesen,
10 (509) 624-4276.

11 I hereby declare that all statements made herein of my own
12 knowledge are true and that all statements made on information and
13 belief are believed to be true; and further that these statements were
14 made with the knowledge that willful false statements and the like so
15 made are punishable by fine or imprisonment, or both, under
16 Section 1001 of Title 18 of the United States Code and that such willful
17 false statement may jeopardize the validity of the application or any
18 patent issued therefrom.

* * * * *

1 Full name of inventor: Werner Juengling

2 Inventor's Signature: Werner Juengling

3 Date: 22-Sept-87

4 Residence: Boise, ID

5 Citizenship: Austria

6 Post Office Address: 5660 S. Tecoma Place
7 Boise, ID 83705

8 * * * * *

9 Full name of inventor: Kirk D. Prall

10 Inventor's Signature: Kirk Prall

11 Date: 8/25/91

12 Residence: Boise, ID

13 Citizenship: USA

14 Post Office Address: 2548 S. Harmony Ave.
15 Boise, ID 83706

16 * * * * *

17 Full name of inventor: Ravi Iyer

18 Inventor's Signature: Ravi Iyer

19 Date: Sept 23/91

20 Residence: Boise, ID

21 Citizenship: India

22 Post Office Address: 5600 S. Fuchsia Ln.
23 Boise, ID 83706

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2 * * * * * * * * * *
3 Full name of inventor: Curtej S. Sandhu

4 Inventor's Signature: Curtej S. Sandhu

5 Date: 8/18/97

6 Residence: Boise, ID

7 Citizenship: U.K.

8 Post Office Address: 2964 E. Parkriver Drive
Boise, ID 83706

11 * * * * * * * * * *

12 Full name of inventor: Guy Blalock

13 Inventor's Signature: Guy Blalock

14 Date: 9/24/97

15 Residence: Boise, ID

16 Citizenship: USA

17 Post Office Address: 3432 Vintage Way
Boise, ID 83706